

Fast-Transient Asynchronous Digital LDO with Load Regulation Enhancement by Soft Multi-Step Switching and Adaptive Timing Techniques in 65-nm CMOS

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Outline

- ❑ **Background and Motivations**
 - Mixed-signal on-chip power management
- ❑ **Review of Fine-grained Digital LDO**
- ❑ **Proposed Asynchronous Digital LDO**
 - Analysis of voltage regulation
 - Soft multi-step switching and adaptive timing
- ❑ **Measurement Results**
- ❑ **Comparison & Conclusions**

Mixed-signal on-chip power management

- ❑ Wide-range: Dynamic voltage and frequency scaling (DVFS)
- ❑ Fine-grained on-chip voltage regulation
- ❑ CPU as the power management supervisor

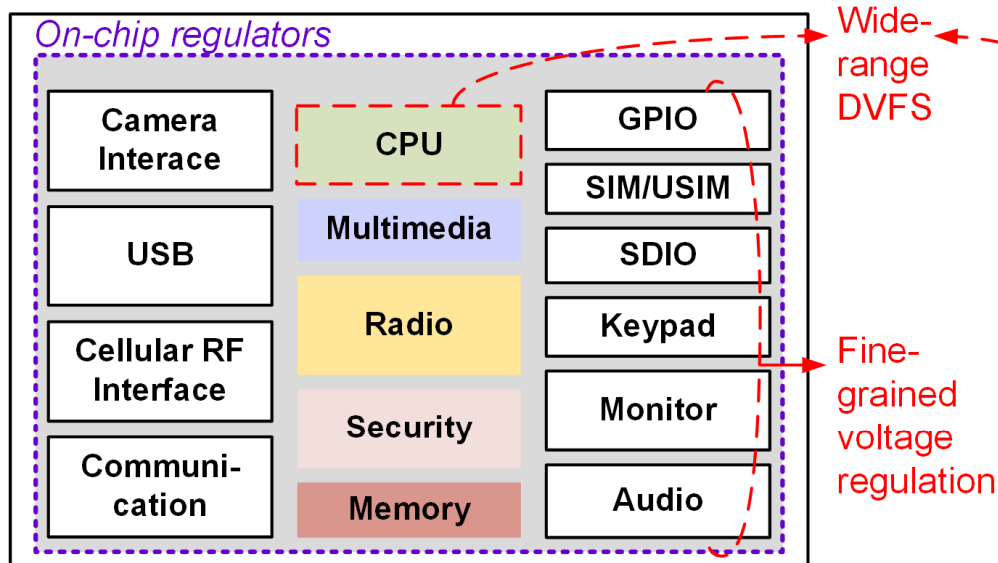


Fig. 1: A Cellular SoC

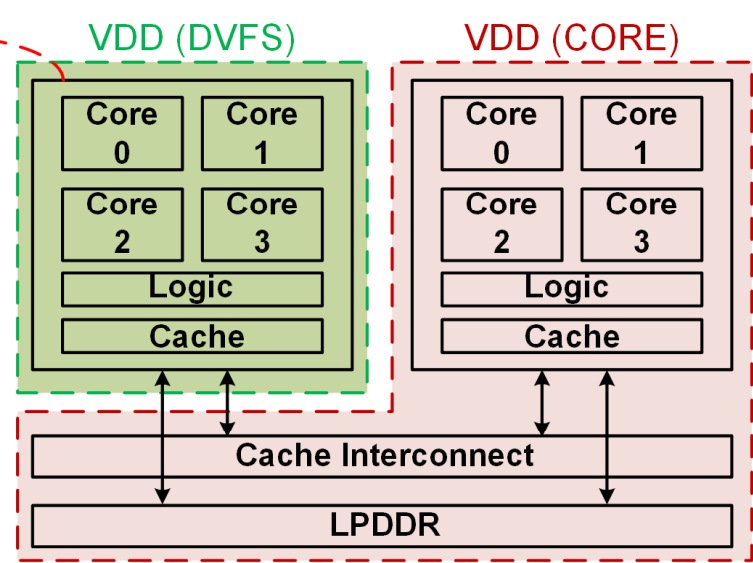


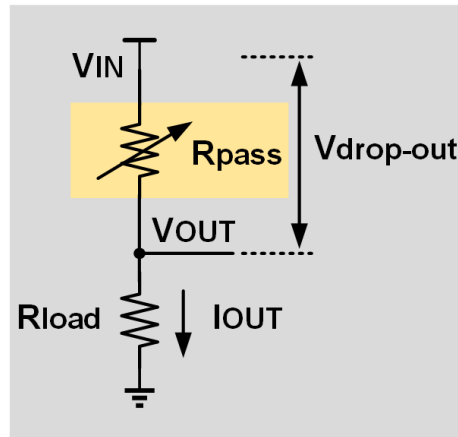
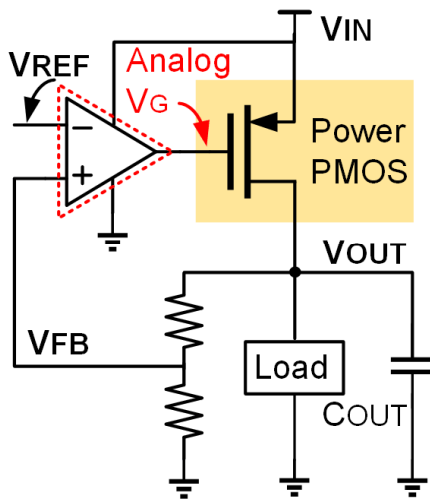
Fig. 2: An Octa-core mobile AP

[X. Jiang, ESSCIRC 2014] [M. Igarashi, ISSCC 2014]

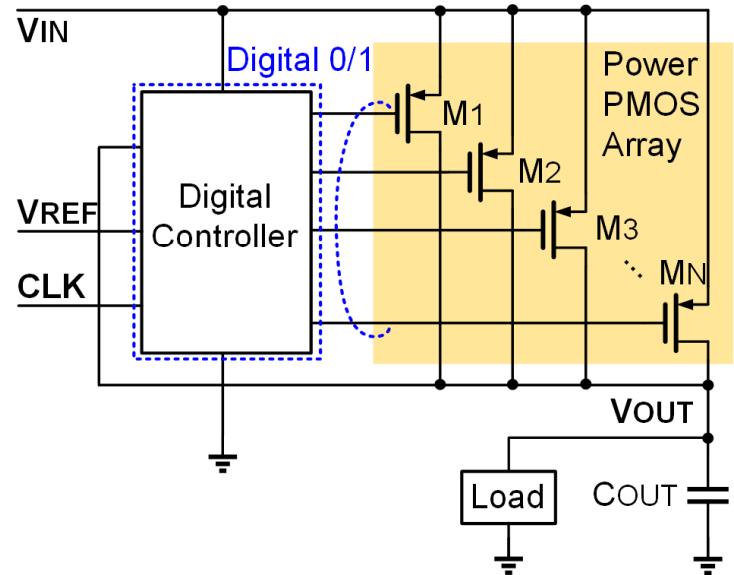
Fine-grained voltage regulation

- Low-dropout regulator (LDO)
 - “Resistor-divider”
 - Fine-grained voltage regulation
 - Controller: **analog** (high-gain) or **digital** (wide range)

Analog LDO

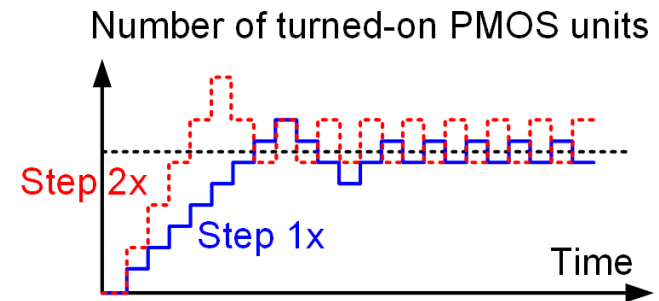
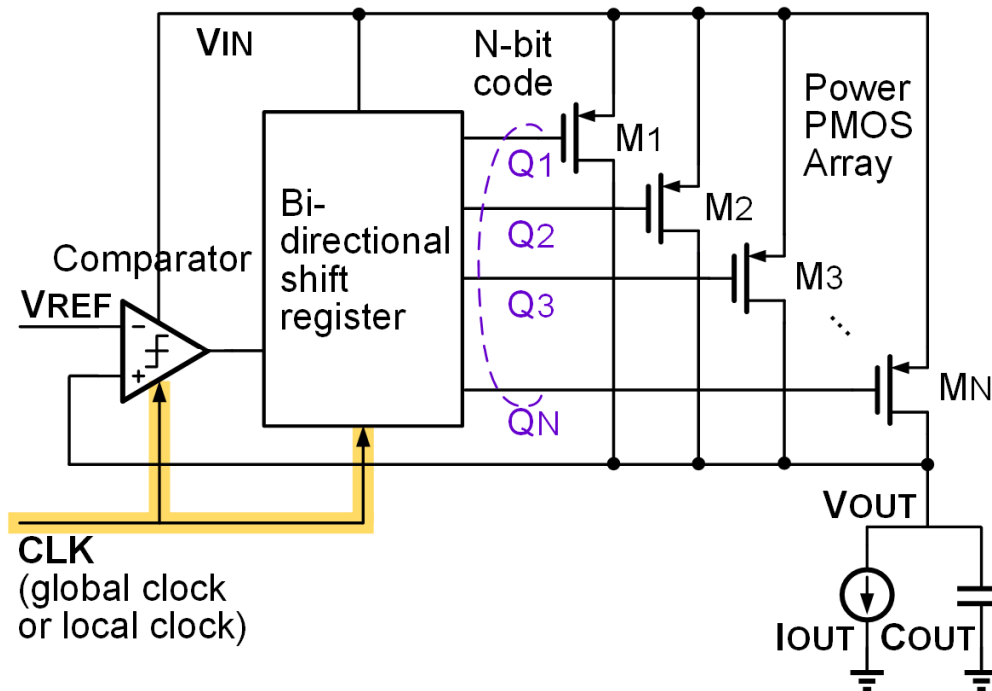


Digital LDO



DAC-ADC-based Digital LDO

- Successive comparison: $V_{out} \sim V_{ref}$
- ✓ **Pros:** Fully synthesizable; Flexibility; PVT robust; Low power
- ✗ **Cons:** Coarse voltage regulation



Step Size Speed Resolution

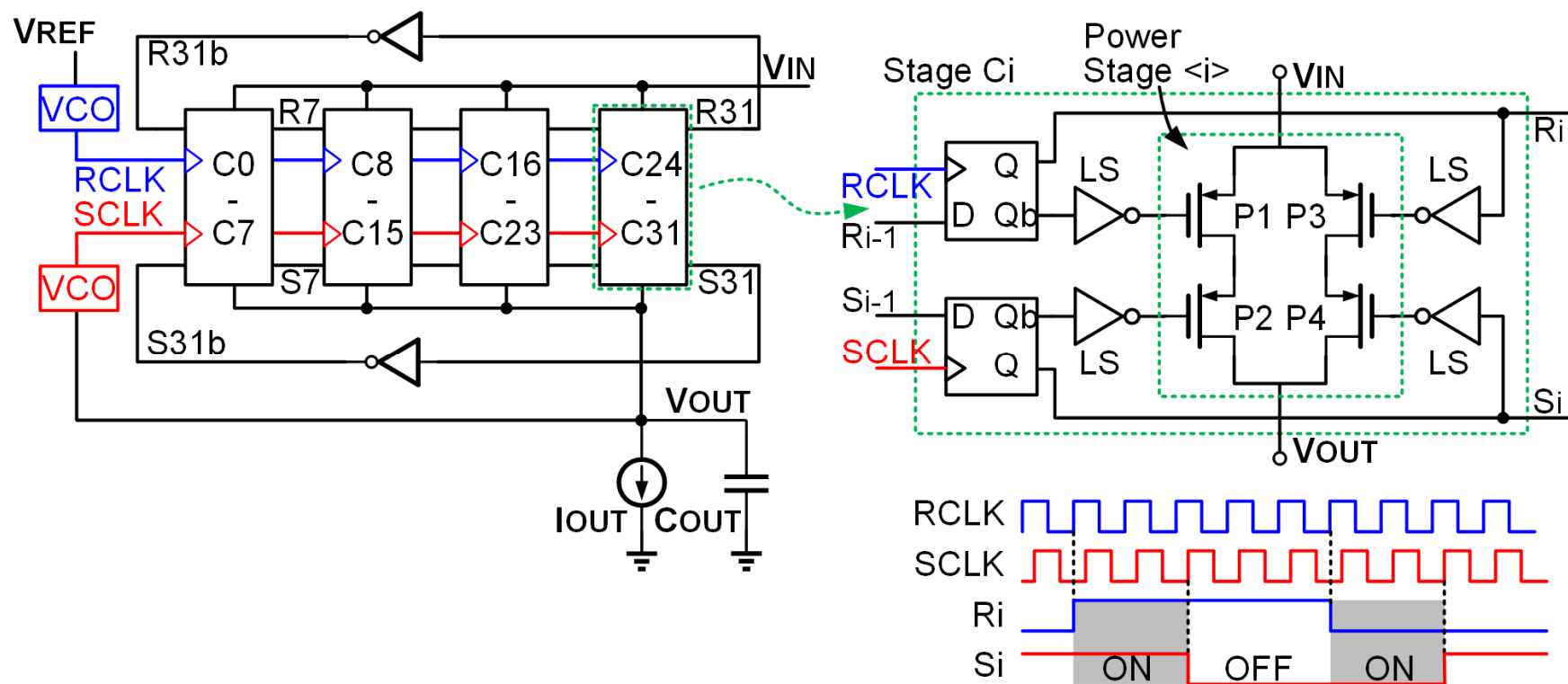
Basic Metrics

- **Speed:** Transient response
- **Resolution:**
Equivalent number of binary bits:
 $\log_2 N$ (N : # of minimum units)

[Y. Okuma, CICC 2010] [Onouchi, ASSCC 2011] [Y.-H. Lee, VLSIC 2012]

VTC-TDC-based Digital LDO

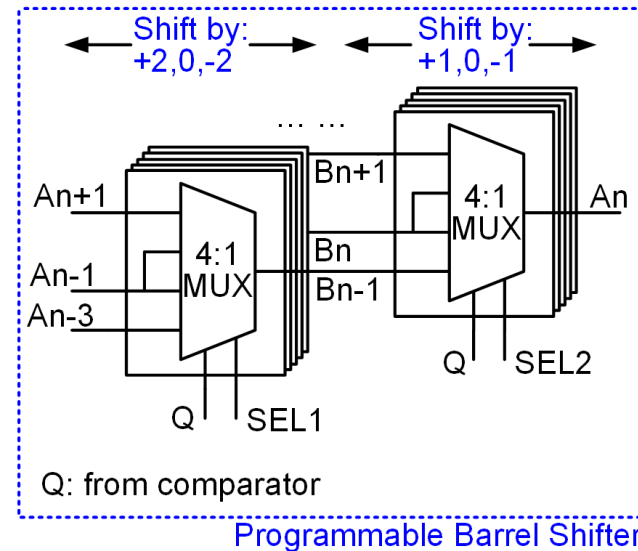
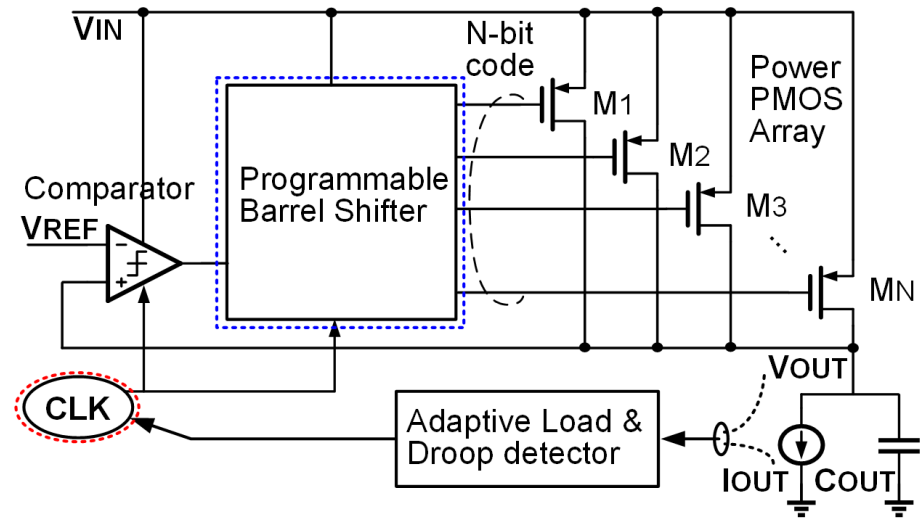
- ❑ Phase locked loop (PLL) locks the phase difference
- ✓ **Pros:** Fine voltage regulation
- ✗ **Cons:** PVT dependency; Less flexibility; High power



[A. Raychowdhury, VLSIC 2012]

Fine/Coarse Regulation: Multiple step size

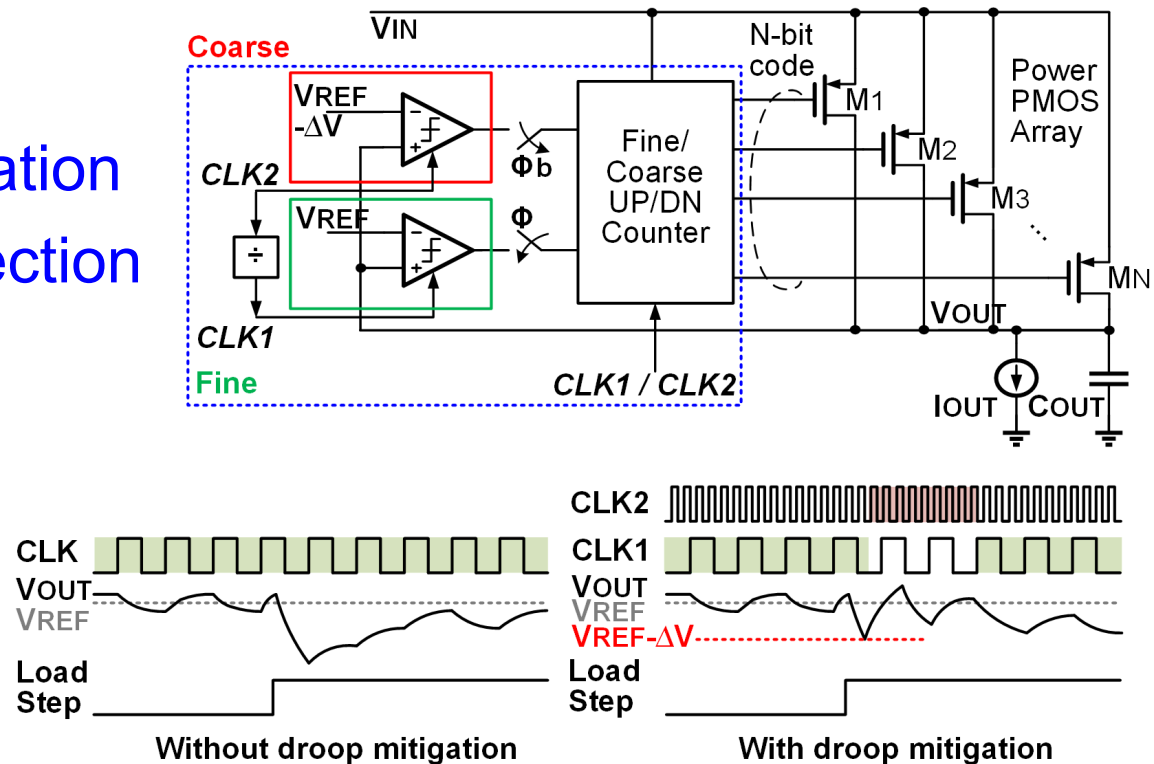
- ❑ Multiple shift step sizes:
 - Loop gain 1x - 3x
- ❑ Adaptive frequency:
 - Large load or step
- ❑ Pros & Cons:
 - ✓ Fine/coarse adaptation
 - ✗ Analog droop detection
 - ✗ Linear improvement
 - ✗ Power hungry



[S. B. Nasir, ISSCC 2015]

Fine/Coarse Regulation: Turbo frequency

- ❑ Dual coarse/fine counting mode:
 - Slow fine clocking for steady state
 - Fast coarse clocking for droop mitigation
- ❑ Droop detection
- ❑ Pros & Cons:
 - ✓ Fine/coarse adaptation
 - ✓ Various droop detection
 - ✗ Droop not scales with supply
 - ✗ Power hungry



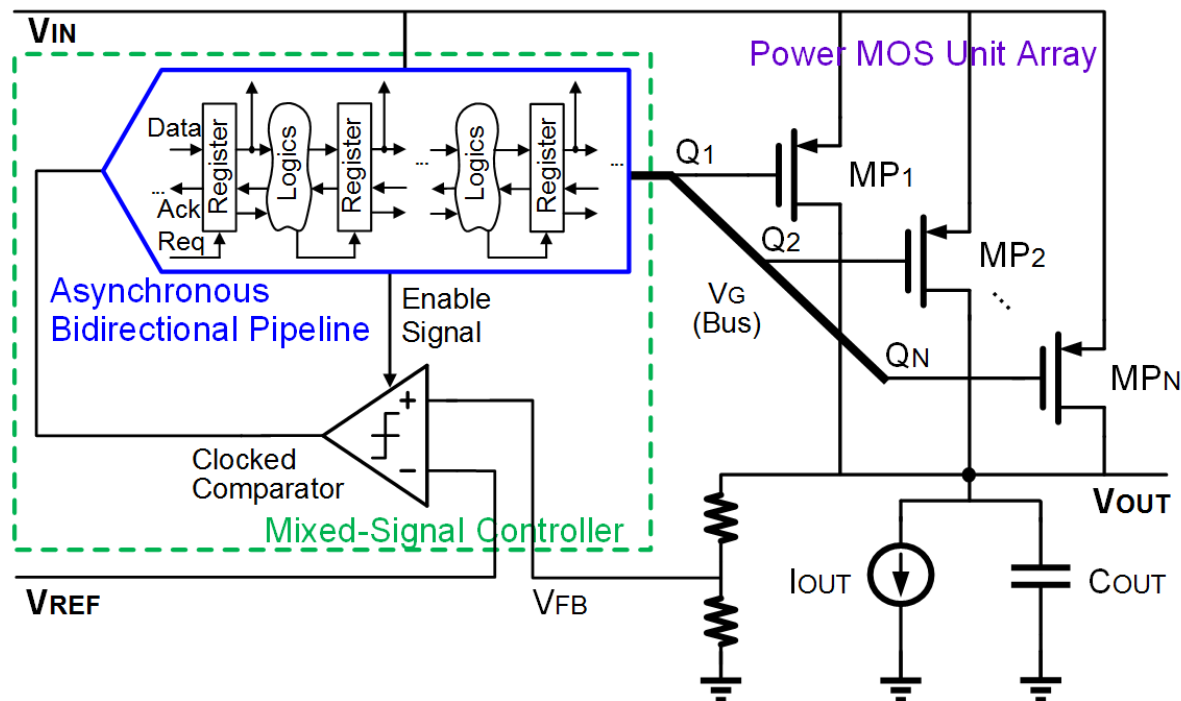
[S. T. Kim, ISSCC 2015]

Any room for improvement?

- ❑ Limited topological innovation
 - ✗ Limited enhancement: linear multiple step size
- ❑ Clock frequency affected by PVT variation
 - ✗ Instability: turbo frequency at large load step
- ❑ Coarse/fine regulation has potential switching problem
 - ✗ Caused by size change or turbo clocking
- ❑ The need is:
 - ✓ Topology balances speed and resolution
 - ✓ Asynchronous “clocking”
 - ✓ Soft coarse/fine mode switching

Architecture of proposed digital LDO

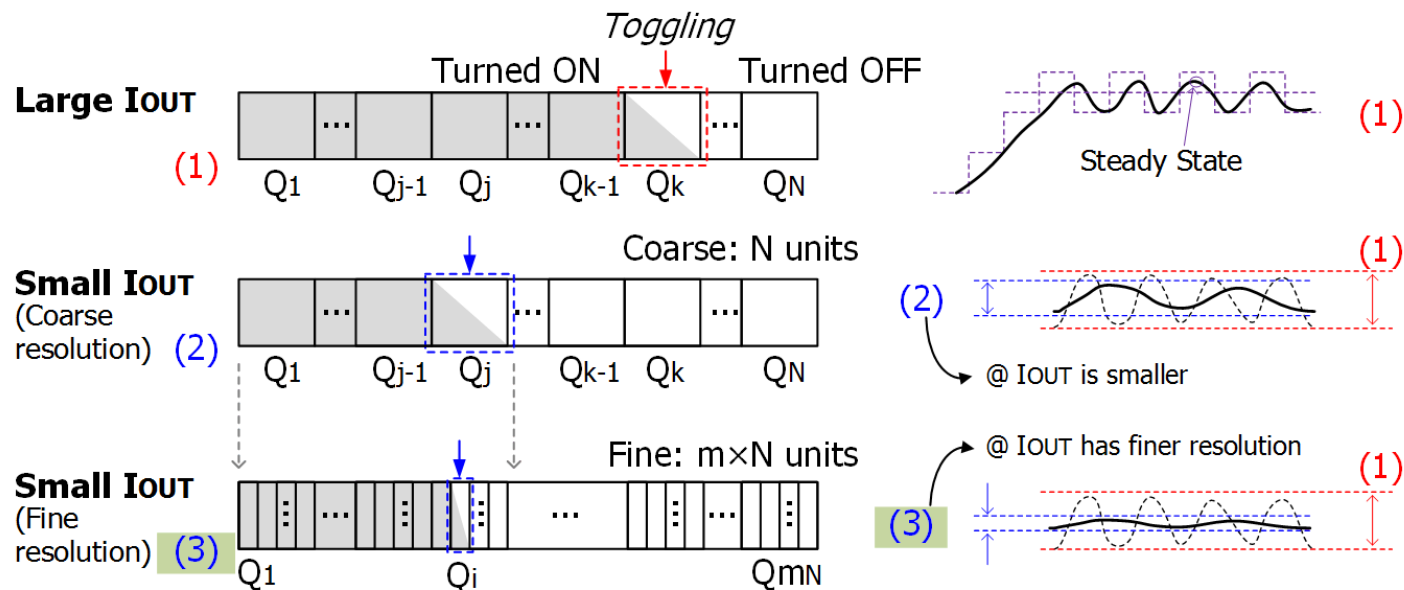
- ❑ Multiple-step-size power stage *
- ❑ Power-efficient speed and regulation enhancement
 - **Regulation++**: soft multi-step switching
 - **Speed ++**: adaptive & **Power--**: asynchronous clock



* [F. Yang, ESSCIRC 2015]

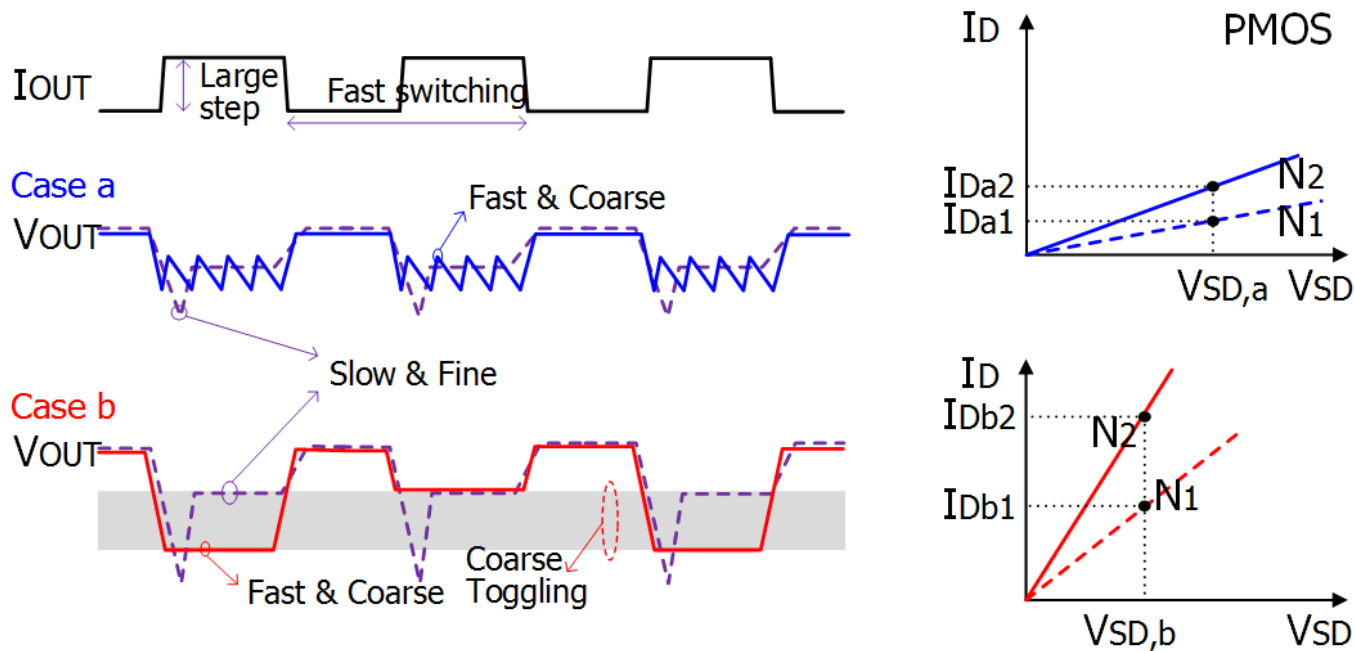
Analysis of steady state voltage regulation

- Steady state digital codes: On, Off, Toggling
- Ripple reduction by multi-step size:
 - Light load: small I_{OUT}
 - Fine resolution: m fine bit per coarse bit (N)
 - Large output capacitor



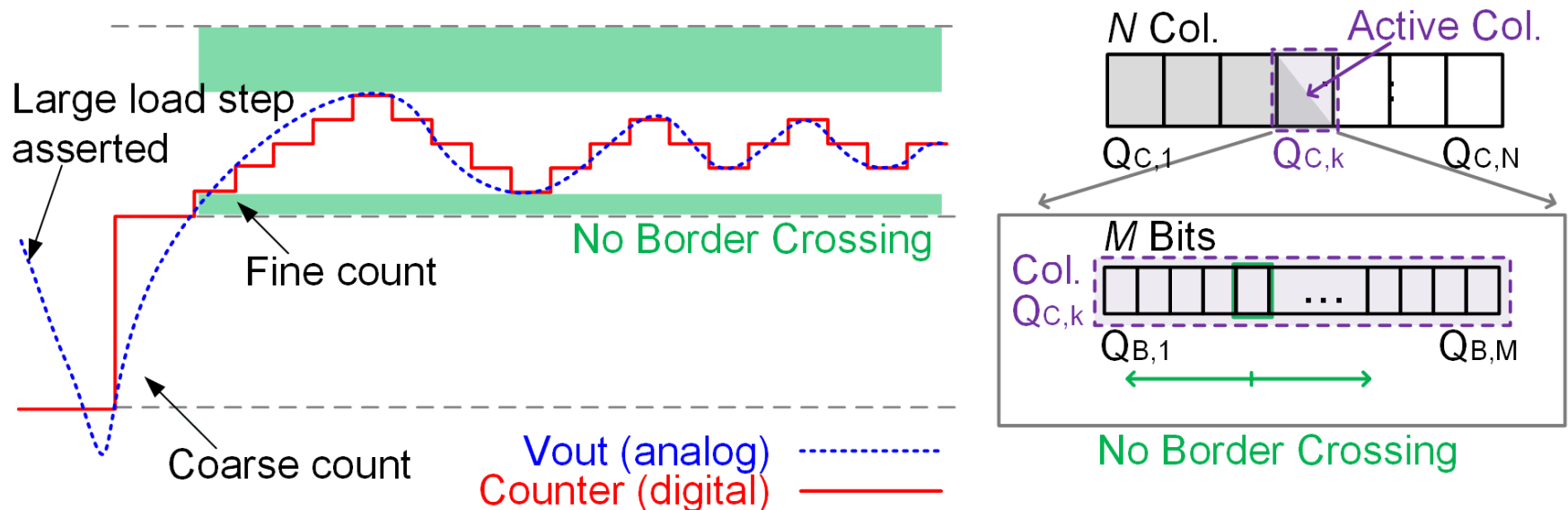
Analysis of in-transient voltage regulation

- Digitally controlled power MOS unit (PMOS)
 - Linear region (when ON), cut-off region (when OFF)
- **Case a:** small ripple \rightarrow regulated in dc
- **Case b:** large ripple \rightarrow regulation error (consecutive toggling)



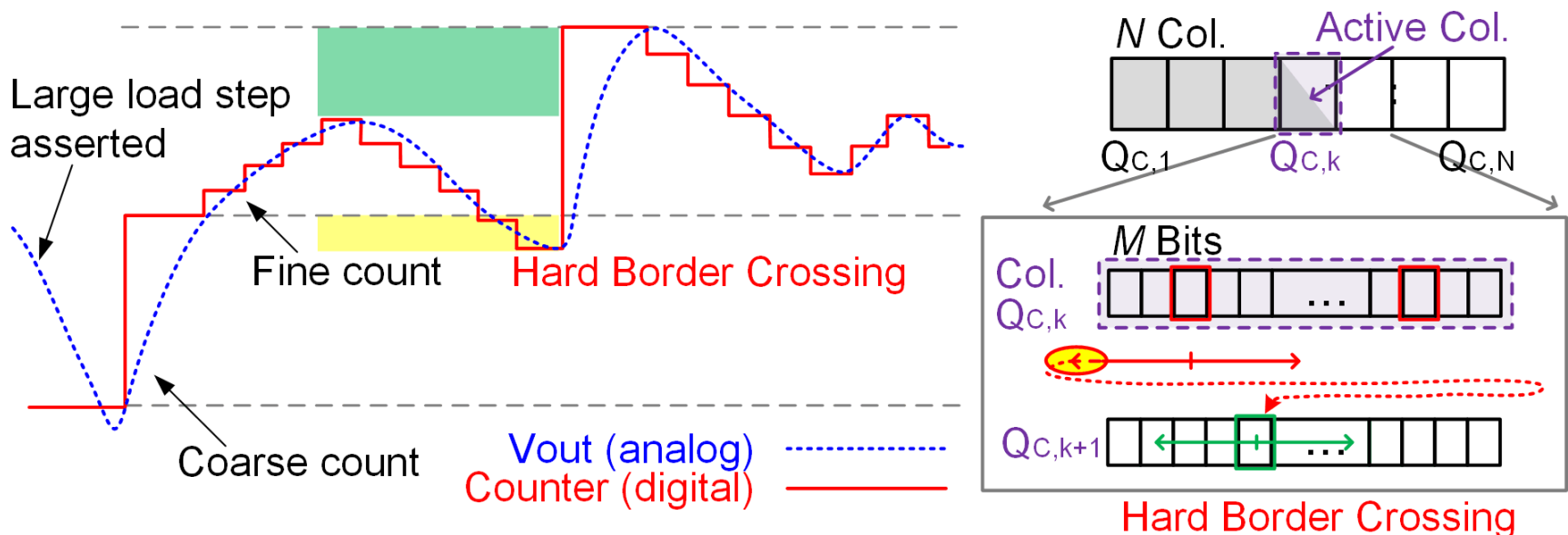
Multi-step switching: No border crossing

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
- ❑ Recovery from voltage droop @ large load step
 - **Case 1: No border crossing**
 - Voltage droop -> Coarse count -> Fine count ... 😊



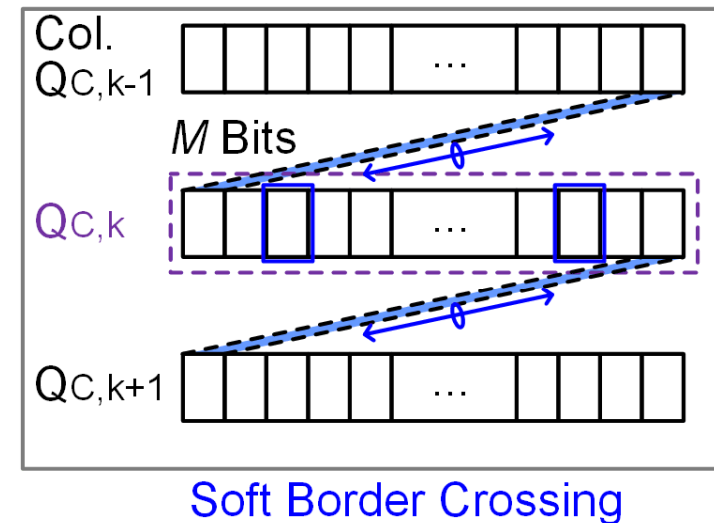
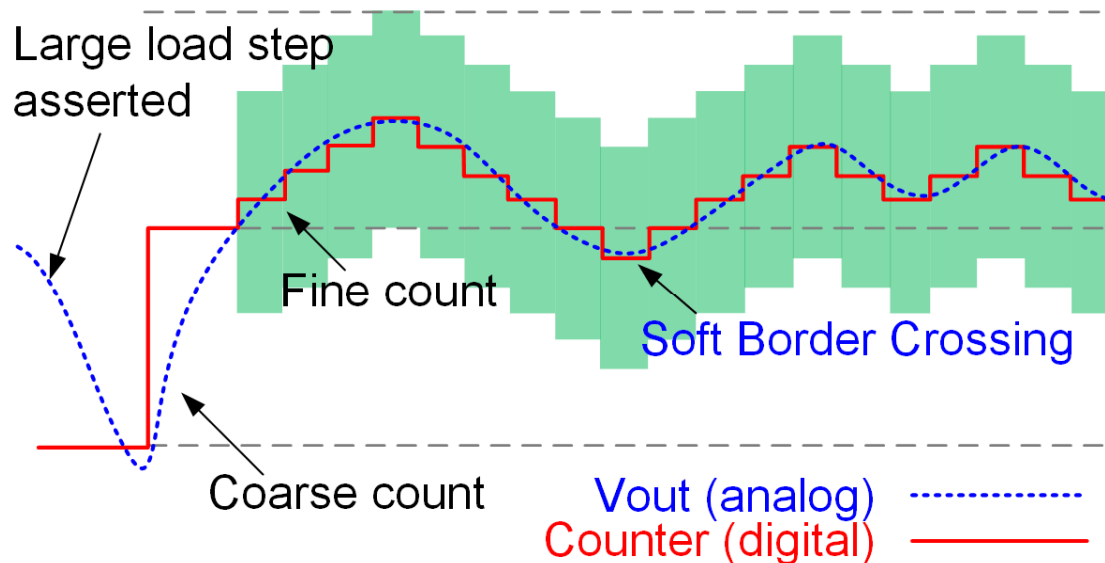
Multi-step switching: Hard border crossing

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
- ❑ Recovery from voltage droop @ large load step
 - **Case 2A: Hard border crossing**
 - Voltage droop -> Coarse -> Fine -> **Coarse count** -> ... ☹️



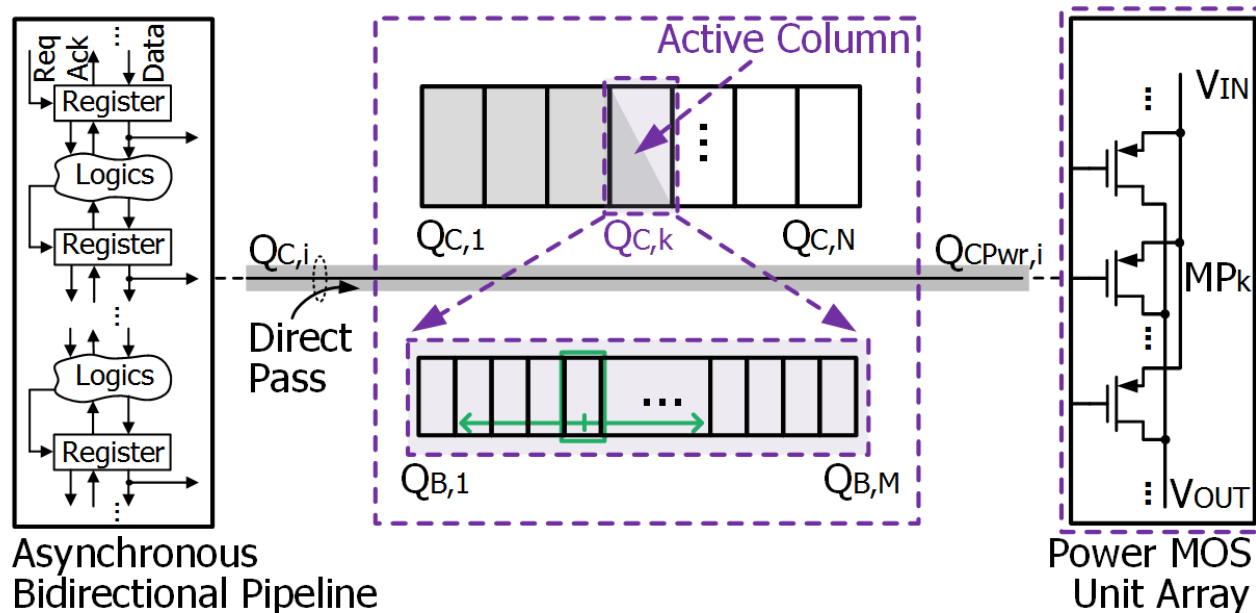
Multi-step switching: Soft border crossing

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
- ❑ Recovery from voltage droop @ large load step
 - **Case 2B: Soft border crossing**
 - Voltage droop -> Coarse count -> Fine count ... 😊



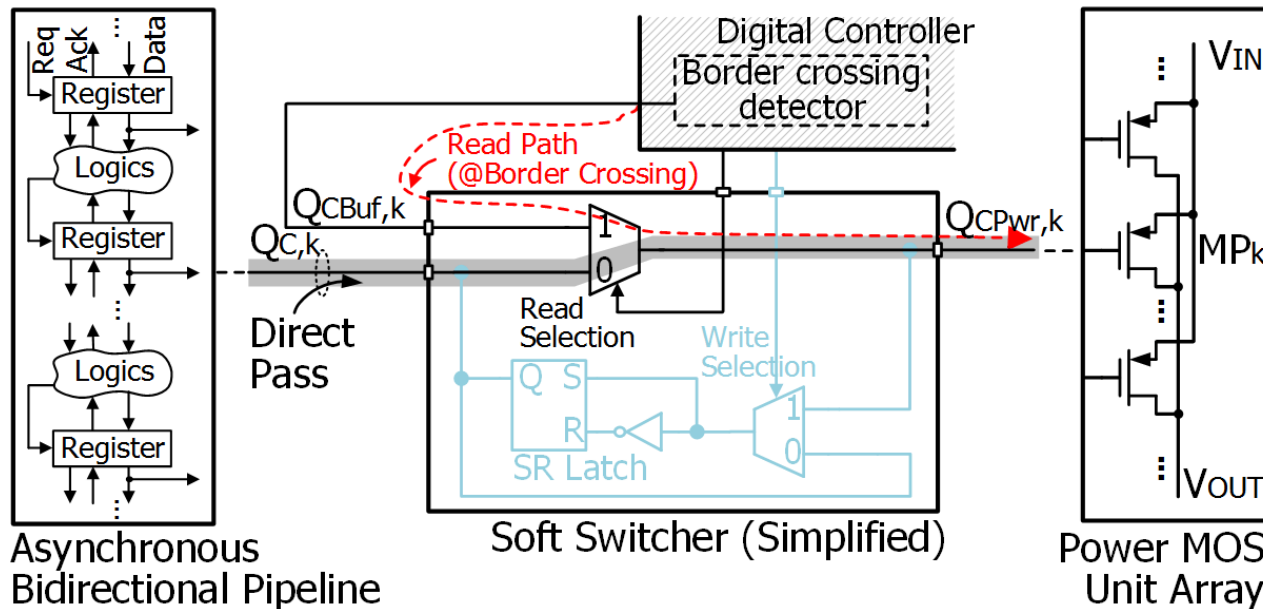
Direct multi-step switching

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
 - **Coarse mode:** locate active column
 - **Fine mode:** last toggling bits
- ❑ Direct pass comparator output $Q_{C,i}$ to power MOS gate $Q_{CPwr,i}$



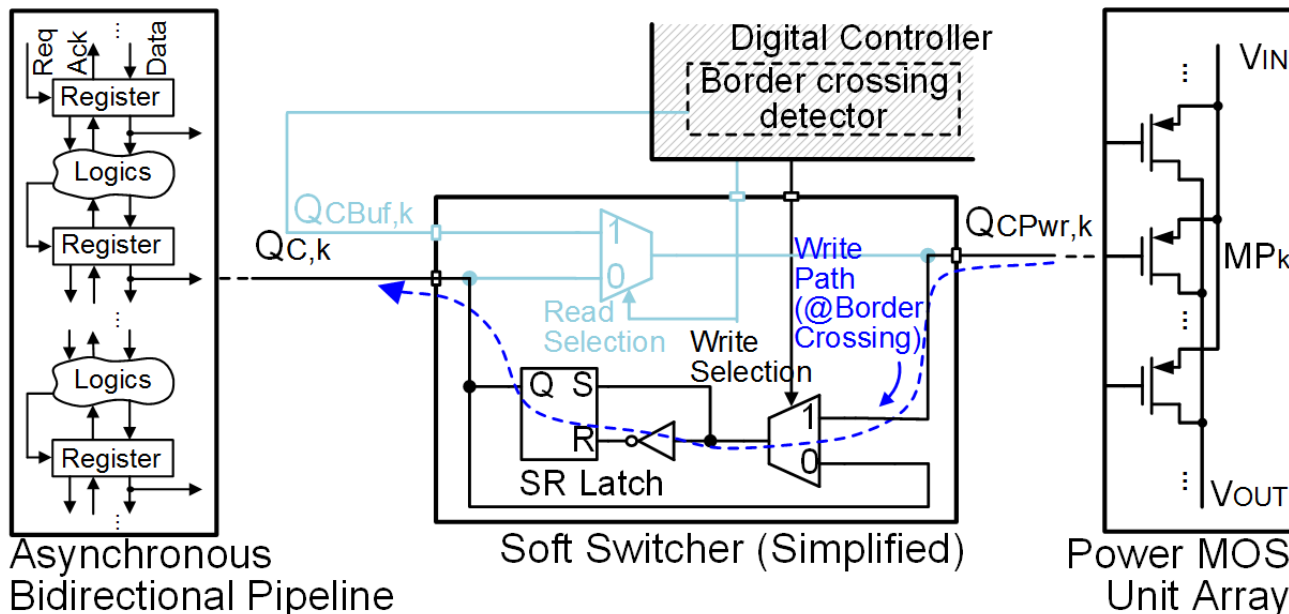
Soft multi-step switching: Read path

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
- ❑ Bi-directional multi-step switching
 - **Read path @ border crossing detected**
 - Adaptively change $Q_{CPwr,k}$ w/o coarse-mode comparison



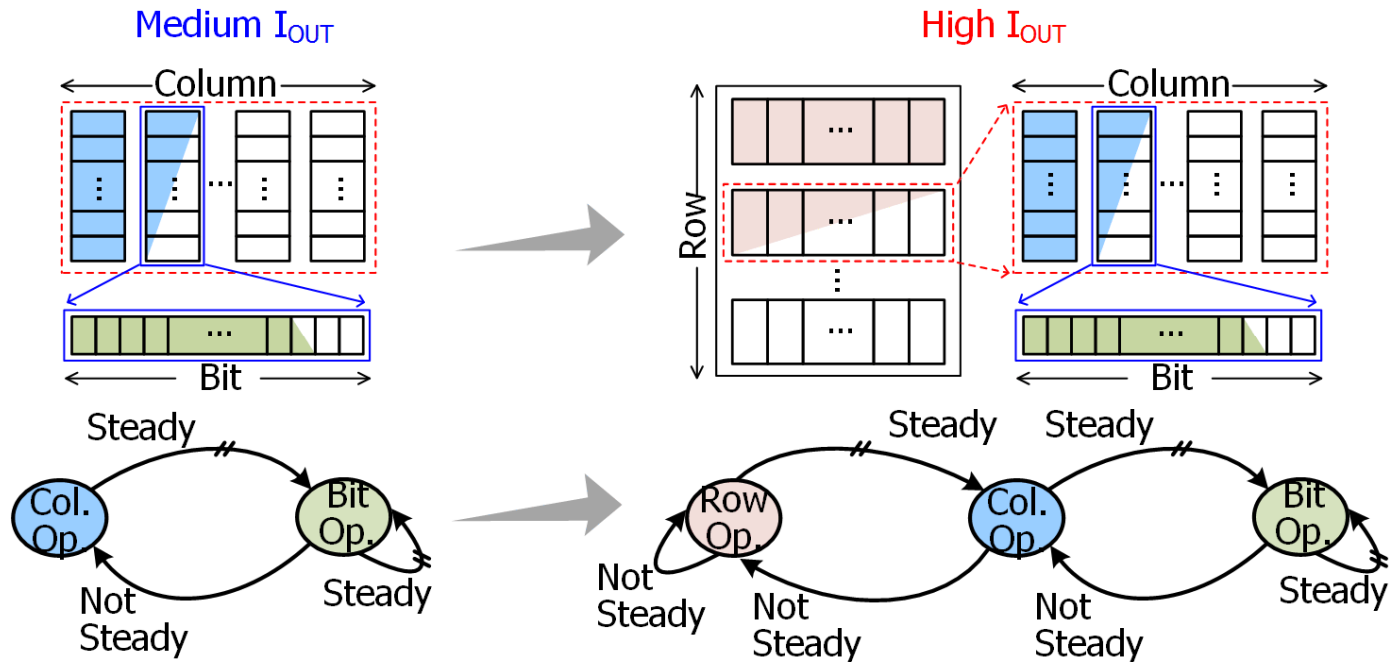
Soft multi-step switching: Write path

- ❑ Scenario: Two-step coarse/fine voltage regulation
 - N columns: each column with M bits
- ❑ Bi-directional multi-step switching
 - **Write path @ border crossing detected**
 - Update $Q_{CPwr,k}$ back to register before coarse-mode starts



Stronger power strength: to Row-Column-Bit

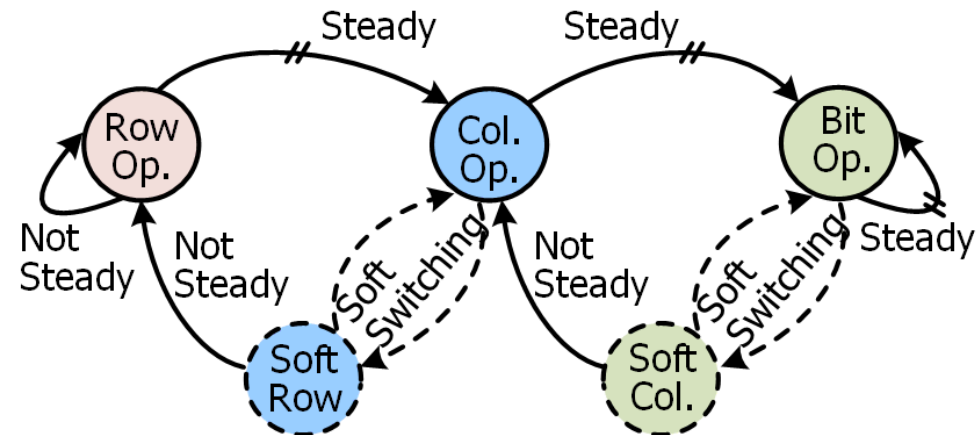
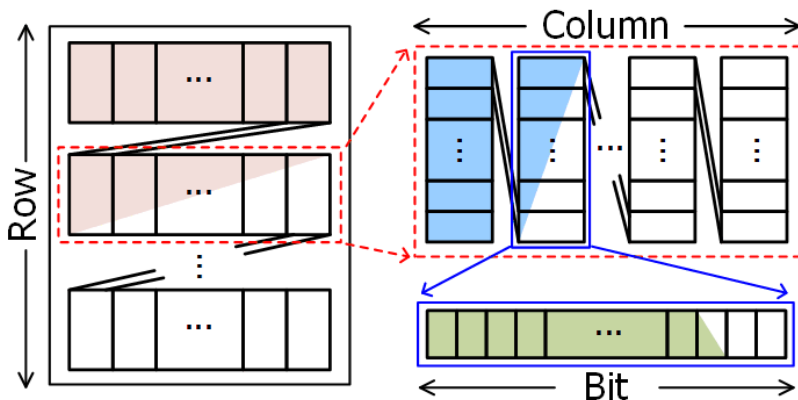
- ❑ Larger output current delivery
 - *Row* virtually defined as grouped *Columns*
- ❑ Coarse/fine mode conducted by Finite State Machine (FSM)
 - Transient enhancer path + Resolution enhancer path



[F. Yang, ESSCIRC 2015]

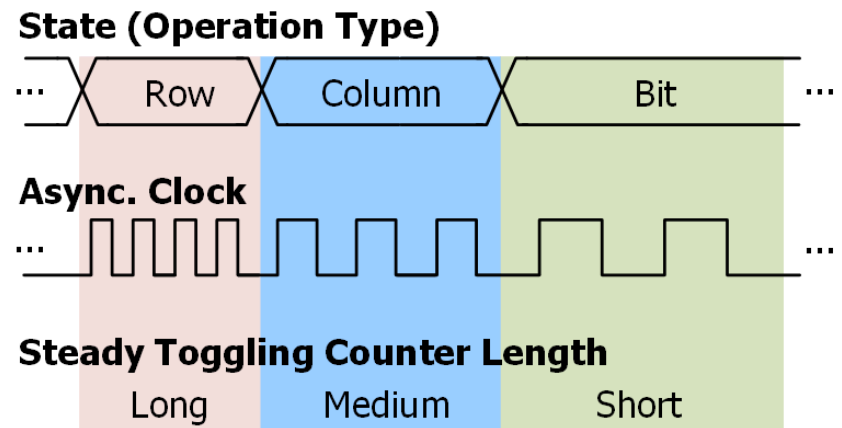
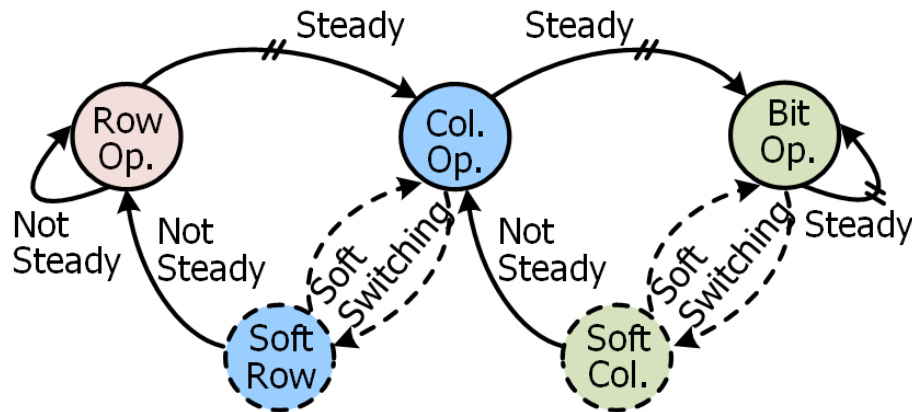
Finite state machine (FSM) with adaptive timing

- ❑ Multi-step switching with richer FSM
 - Column operation \leftarrow Soft Column \leftrightarrow Bit operation
 - Row operation \leftarrow Soft Row \leftrightarrow Column operation
- ❑ FSM state transition: internal counter



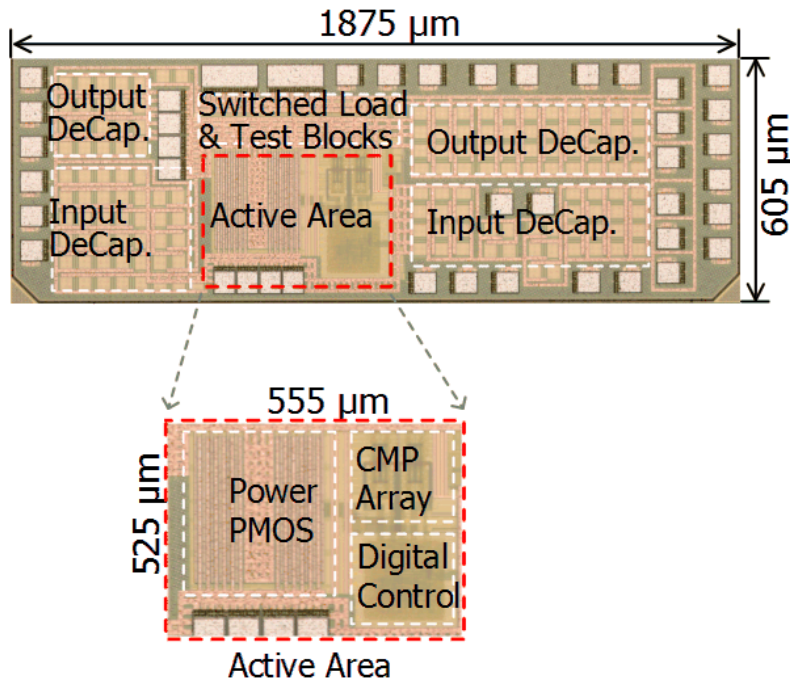
Finite state machine (FSM) with adaptive timing

- ❑ FSM state transition: internal counter
- ❑ **Adaptive timing in FSM**
 - Power strength consideration
 - Long (Row) /Medium (Column) /Short (Bit)



The chip and Specification

Chip micrograph



CMP: comparator
DeCap: decoupling capacitor

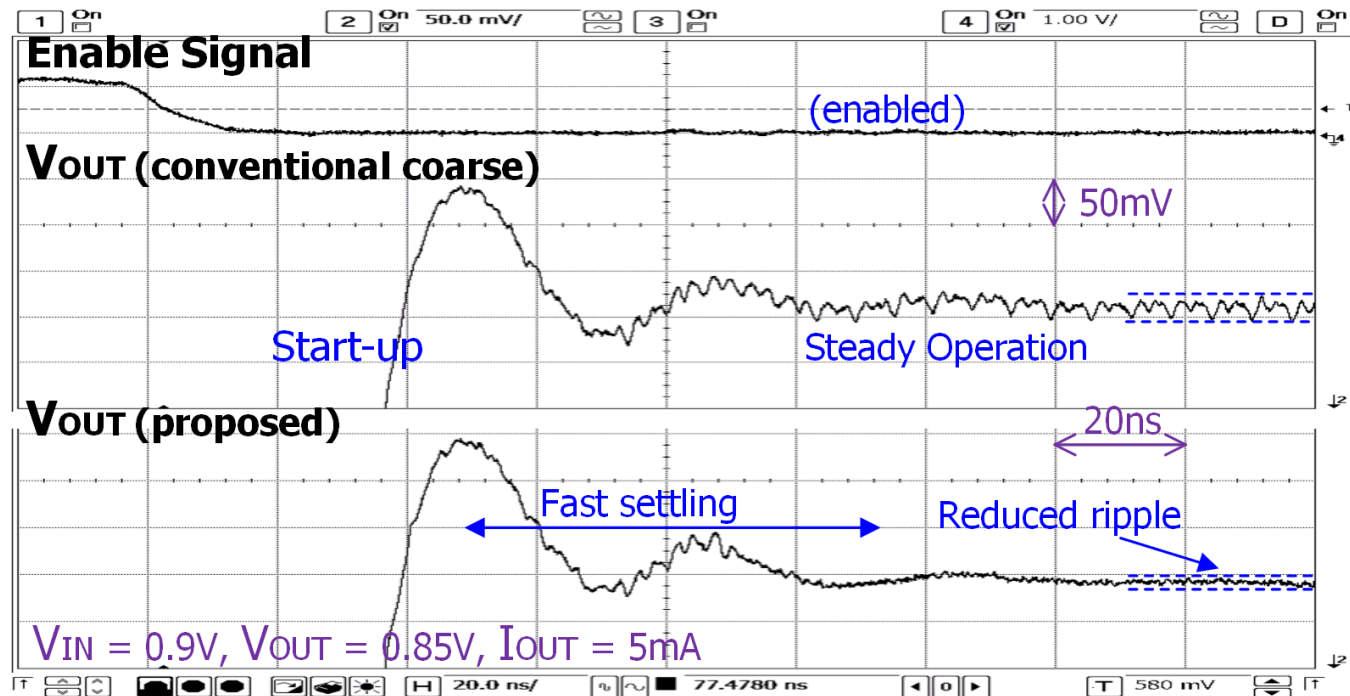
Specification

Technology	65nm LL
Input voltage	0.6 – 1.0V
Output voltage	0.55 – 0.95V
Maximum output current	500mA
Load capacitor	2nF
Control method	Asynchronous digital control
Equiv. binary bits	9.5 *
Quiescent current	350 μA
Transient edge	2ns

* 9.5 is calculated from: $\sim \log_2(6 \times 8 \times 16)$

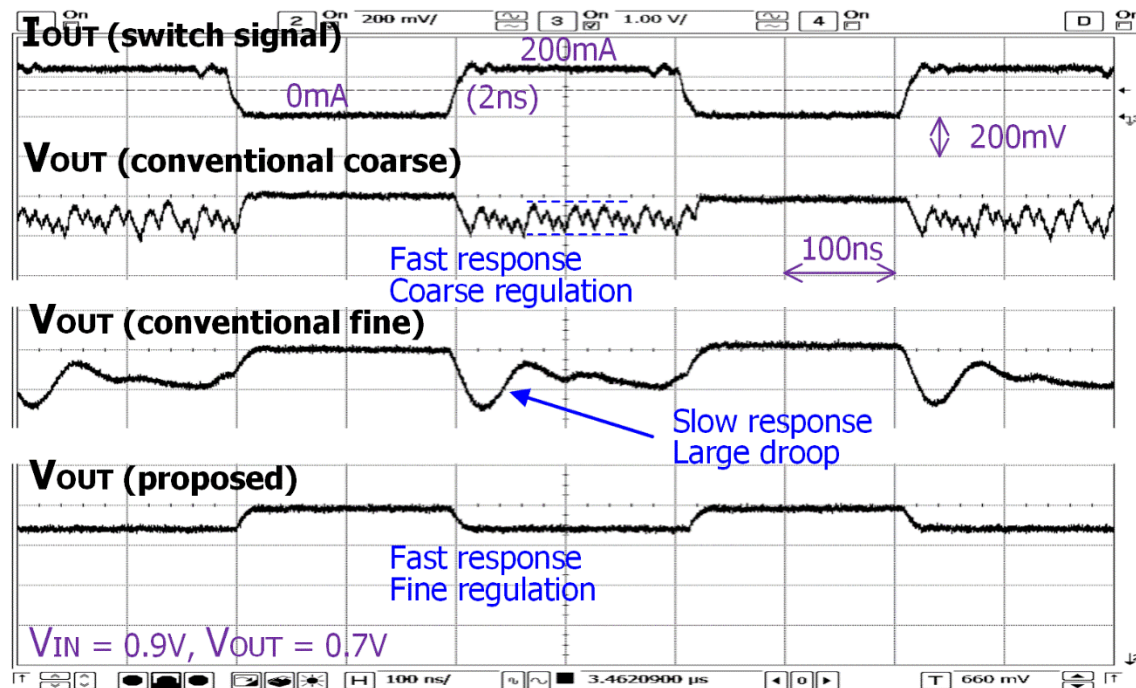
Measured start-up and steady operation

- Comparison with:
 - Conventional design with coarse-grained regulation
- Comparable fast settling time



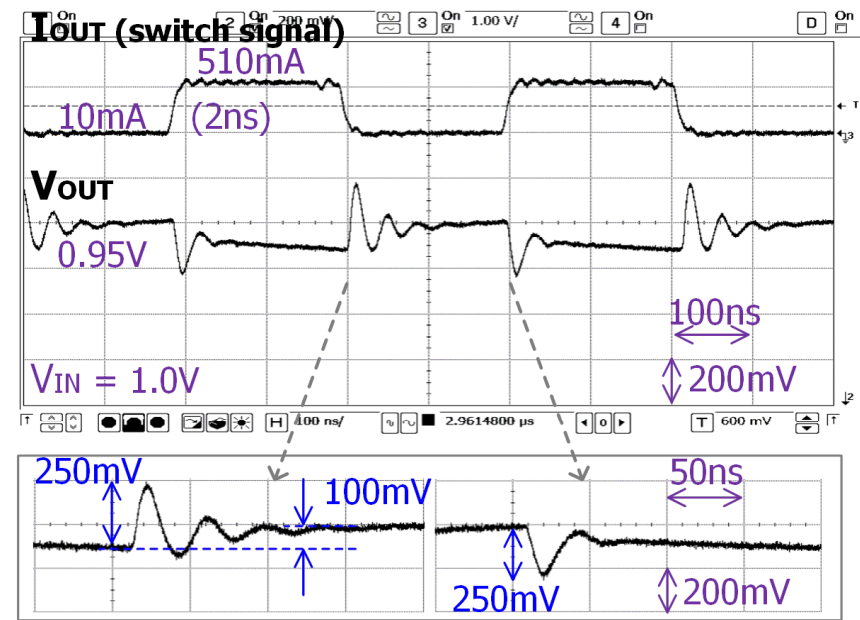
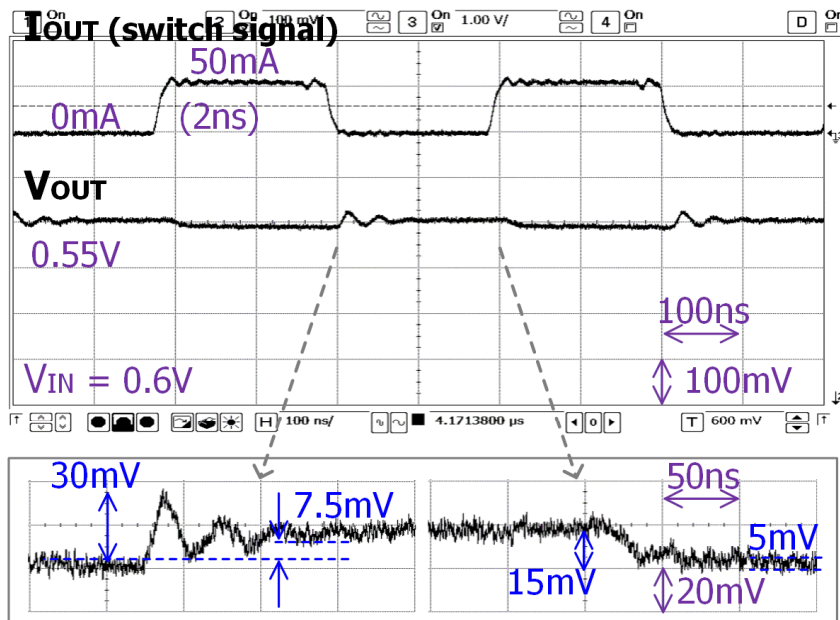
Measured load transient response (for comparison)

- ❑ Comparison with:
 - Conventional design: coarse-grained or fine-grained **only**
- ❑ Faster transient response and smaller droop
- ❑ Finely regulated output voltage



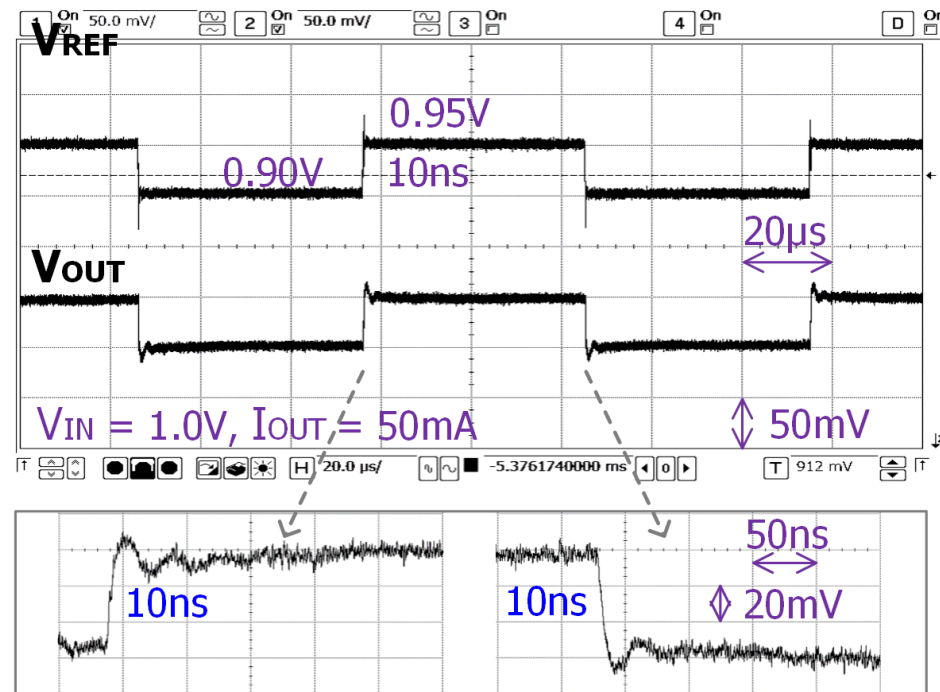
Measured Transient Response

- Measured load transient response
 - 50mA on-chip current step
 - 500mA on-chip current step



Measured Transient Response

- Measured reference tracking
 - 0.9 - 0.95V (50mV) reference voltage step at $V_{IN} = 1.0V$, $I_{OUT} = 50mA$



Comparison of Performance

Publication	Hazucha JSSC'07	Okuma CICC'10	Onouchi ASSCC'11	Oh TVLSI'14	Gangopadhyay JSSC'14	Nasir ISSCC'15	This Work
Technology	90nm	65nm	40nm	110nm	32nm	130nm	65nm
V_{IN} (V)	2.4	0.5	1.34	0.6-1.2	0.7-1.0	0.5-1.2	0.6-1.0
V_{OUT} (V)	1.2	0.45	1.20	0.5-0.9	0.5-0.9	0.45-1.14	0.55-0.95
$I_{OUT,MAX}$ (mA)	1000	0.2	250	80	5	4.6	500
Equiv. bin-bits	4	8	5.8 ⁽²⁾	9	N/A	7	9.5
C_{OUT} (nF)	2.4	100	N/A	1	0.1	1	2
Edge Δt (ns)	0.288	N/A	5	25000 ⁽²⁾	10 ⁽²⁾	N/A	2 ⁽¹⁾
ΔI_{MAX} (mA)	1000	0.2	114	80	0.8	1.4 ⁽²⁾	500
ΔV_{OUT} (mV)	120	40	50	53	150	90 ⁽²⁾	250
Load reg. (mV/mA)	N/A	0.65	N/A	0.30	N/A	10	0.15-0.2
Quiescent I_Q (μA)	25700	2.7 (1MHz)	10000 (1GHz)	32	92	24-221	350
FOM_T (ps) ⁽³⁾	7.4	270000	6140.4	0.27	1150	8571 ⁽²⁾	0.7
FOM_V (V) ⁽⁴⁾	0.0031	N/A	0.076	1.840	0.599 ⁽²⁾	N/A	0.0012

(1) Simulated data (2) Estimated from figure or content

(3) $FOM_T = (C_{OUT} \times \Delta V_{OUT} \times I_Q) / \Delta I_{MAX}^2$ or $T_R \times I_Q / \Delta I_{MAX}$ (if T_R given)

(4) $FOM_V = K(\Delta V_{OUT} \times I_Q) / \Delta I_{MAX}$

Conclusions

- ❑ **Proposed a 65-nm asynchronous digital LDO**
 - Nanoseconds' transient response over 500 milli-amperes
 - 9.5b fine resolution, 0.6V to 1V input voltage range
 - improved load regulation
- ❑ **Featured soft coarse/fine multi-step switching**
 - Adaptive to wide load: multiple-step-size power stage
 - Asynchronous pipeline with adaptive size and timing
 - Soft switching between coarse/fine modes
- ❑ **State-of-the-art Figure of Merits (FOM_T and FOM_v)**

Acknowledgement

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